

Product Change Notification - KSRA-16NLUE680

Date:

13 Aug 2019

Product Category:

Notification subject:

CCB 3863 Final Notice: Implement Microchip marking changes for selected Microsemi (PoE, PM and SNR) products

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN # Affected CPN.

Note 1: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Note 2: As part of the integration process additional products may be identified that were not part of the original list.

Description of Change:

Implement Microchip marking changes for selected Microsemi products within the Microsemi subsidiaries Microsemi Solutions Sdn.Bhd. (which formerly Power over Ethernet, Power Management, and Sensors

Pre Change:

Microsemi top marking format and traceability code

Post Change:

Microchip top marking format and traceability code

Pre and Post Change Summary:

| | PRE CHANGE (Microsemi) | POST CHANGE (Microchip) | | | | |
|--|--|--|--|--|--|--|
| Top mark | Microsemi top marking format and traceability code | Microchip top marking format and traceability code | | | | |
| See attached pre and post marking guidelines | | | | | | |

Impacts to Data Sheet:

Where applicable

Change Impact:

None

Reason for Change:

To improve manufacturability and traceability by standardizing marking format for selected Microsemi products as part of the integration of Microschip and Microsemi.

Change Implementation Status:

In Progress

Earliest Implementation Date:

November 1, 2019

Note: The earliest implementation date is the earliest date that we may implement any combination



of the changes listed in this PCN as we will not implement any of the proposed changes prior to this date. After the earliest implementation date these changes may occur to any product over the course of many months depending on inventory levels and business conditions.

Time Table Summary:

| | Ausgust 2019 | | | | | November 2019 | | | | | |
|---------------------------------|--------------|--|----|----|----|---------------|----|----|----|--|--|
| Workweek 31 32 33 34 35 | | | 35 | -> | 44 | 45 | 46 | 47 | 48 | | |
| Final PCN Issue Date | | | X | | | | | | | | |
| Estimated Implementation Date | | | | | | | Х | | | | |

Method to Identify Change:

Traceability, top marking

Contact Microchip:

You may contact your local <u>Microchip Sales and Distribution</u>. Contact information is also provided on the attached Frequently Asked Questions (FAQ).

If applicable, please also copy your local Microchip field sales and/or field quality representative

Revision History:

August 13, 2019: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

Frequently Asked Questions Microsemi November.pdf

PCN_KSRA-16NLUE680_Affected CPN List.pdf

PCN KSRA-16NLUE680 Pre and Post Changes Marking guidelines.pdf

PCN_KSRA-16NLUE680_Affected CPN List.xlsx

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

| DON KCDA 4CNILLIFCOO |
|----------------------------------|
| PCN_KSRA-16NLUE680 |
| CATALOG_PART_NBR |
| PD70201ILQ-TR |
| PD70100ILD-TR |
| PD70101ILQ-TR |
| PD69108FILQ-TR |
| PD69104ILQ-TR |
| PD69104B1FILQ-TR |
| PD69108ILQ-TR |
| PD69101ILQ-TR |
| PD70200ILD-TR |
| PD69104B1ILQ-TR |
| PD69104FILQ-TR |
| PD69208T4ILQ-TR-LE |
| PD70200ILD-13181TR |
| PD70211ILQ-TR |
| PD81101ILQ-TR-LE |
| PD69101ILQ-13155TR |
| PD69208MILQ-TR-LE |
| PD70224LILQ-TR |
| PD70210ALILQ-TR |
| PD69204T4ILQ-TR-LE |
| PD70210AILD-TR |
| PD70224ILQ-TR |
| PD70210ILD-TR |
| AA540F-01-1016-G-LF |
| AA540F-01-1416-G-LF |
| AA550C2-01-1104-G-LF |
| AA568C1-01-1016-G-LF |
| AA576B-01-1612-GLFTR |
| AA585B-01-2548-GLF-TR |
| AA598D1-01-1416-G-LF |
| AA623B-01-2724-GLFTR |
| AA800A V1R6-01-1416-GLF-13165-TR |
| AAC243E-S8A-G-LF-TR |
| AAP661AS-M5A-GLF-TR |
| AAP661BS-M5A-GLF-TR |
| AAP661CS-M5A-GLF-TR |
| AAP803A1 |
| |
| AAP803A3 |
| LX13084AILQ-TR |
| LX3301AQPW |
| LX3301AQPW-13172 -TR |
| LX3301AQPW-TR |
| LX3302AQPW |
| LX3302AQPW-TR |
| LX3302QPW-TR |
| LX7165-01CSP-TR |

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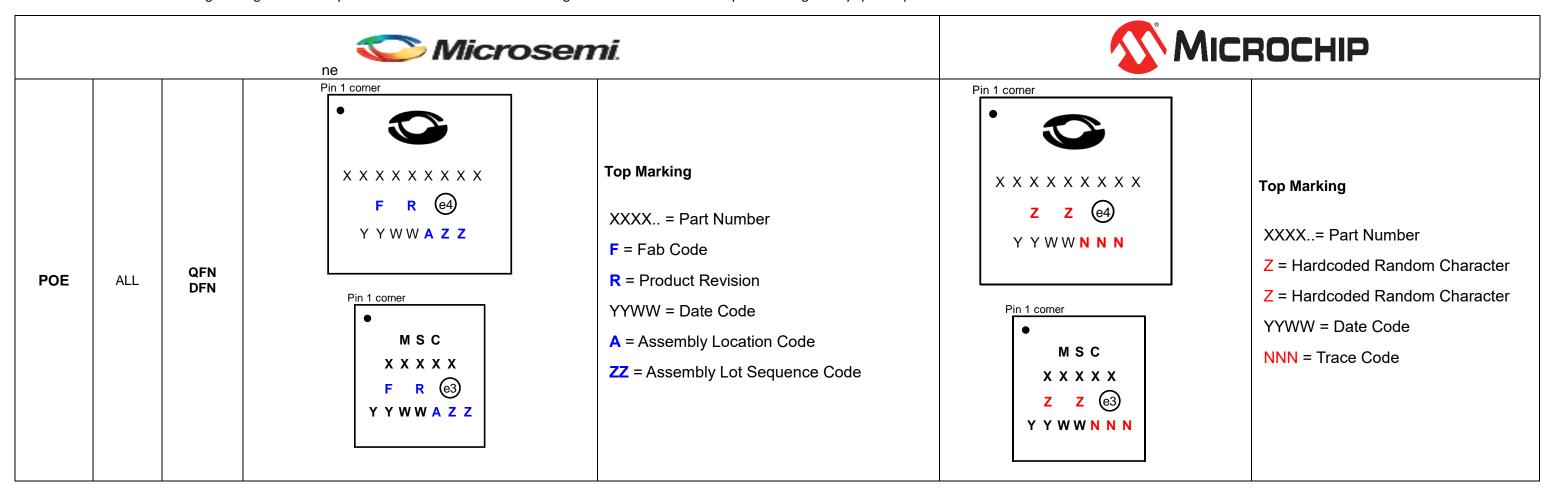
Affected Catalog Part Numbers (CPN)

| PCN_KSRA-16NLUE680 |
|--------------------|
| CATALOG_PART_NBR |
| LX7165-02CSP-TR |
| LX7165-03CSP-TR |
| LX7165-05CSP-TR |
| LX7167ACLD-TR |
| LX7167CLD-TR |
| LX7176ACLQ-TR |
| LX7176CLQ-13162-TR |
| LX7178-01CSP-TR |
| LX7180A-01CLQ-TR |
| LX7180A-11CLQ-TR |
| LX7180A-21CLQ-TR |
| LX7180A-31CLQ-TR |
| LX7219-01ILQ-TR |
| LX7219-02ILQ-TR |
| LX7220-03ILQ-TR |
| LX7302CLQ-TR |
| LX7309ILQ-TR |
| LX802AQDB-TR |
| LX802QDB-TR |
| LX810SDB-TR |
| LX813QPW-TR |
| LX8237ILQ-TR |
| LX8237ILQ-TR-V2R3 |
| LX8237ILQ-TR-V3R2 |
| LX8240ILD-TR |
| LX8259-03ILQ-TR |
| NX9548ILQ-TR |

| | | | ne | Microse | MICROCHIP | | | |
|---------------------|----------------------------|------------|---|-----------------------|--|--|---|--|
| Business Unit(s) | Affected Package(s) | | Pre-Change Marking Diagram (Microsemi) | | Pre-Change Marking Guidelines (Microsemi) | Post-Change Marking Diagram (Microchip) | Post-Change Marking Guidelines (Microchip) | |
| | 2X2 | QFN DFN | • XXXX YWWL | XXXX YWWL | Top Mark Line 1= XXXX Part Number Line 2 = Date Lot Code (YWWL) ● = Pin 1 location Where YWWL is date lot code | • XXXX YNNN YNNN | Top Mark Line 1= XXXX Part Number Line 2= YNNN (trace code) | |
| PM | 2x3 3x2 3x3 WLCSP | QFN DFN | • MSC V XXXX YWWL | XXXX YWWL • MSC | Top Mark Line 1= Pin 1 + Logo + V Line 2 = CPN name Line 3 = Date Lot Code (YWWL) Top Mark Line 1 = CPN name Line 2 = Date Lot Code (YWWL) Line 3= Pin 1 + Logo ● = Pin 1 location Where YWWL is the date lot code V is optional product variation code | MSC V XXXX YNNN MSC | Top Mark Line 1= Pin 1 + Logo +V Line 2 = CPN name Line 3 = Trace code (YNNN) Top Mark Line 1 = CPN name Line 2 = Trace code (YNNN) Line 3= Pin 1 + Logo • = Pin 1 location Where YNNN is the trace code | |
| | 4x4 5x4 5x5 | QFN | •MSC XXXX YYWV | | Top Mark Line 1= Pin 1 + Logo Line 2 = CPN name Line 3 = Date Lot Code (YYWWWLL) • = Pin 1 location Where YYWWLL is the date lot code | • MSC XXXX YWWNNN | Top Mark Line 1= Pin 1 + Logo Line 2 = CPN name Line 3 = Trace Code (YWWNNN) ■ = Pin 1 location Where YWWNNN is the trace code | |
| | 8L | SOIC | XXXXXX XXXXXX FFFFFFF • YYWW | XX F | Top Mark XXXX = MCHP/Customer Part Number FFFF = Fab Code YYWW = Date Code ● = Pin 1 location | XXXXXXX XXXXXXX YYWWNNN • YYWW | Top Mark XXXX= MCHP/Customer Part Number YYWW= Date Code YYWWNNN = Trace Code • = Pin 1 location | |

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|---------------------|---|---------------------|--|---|--|--|--|
| Business Unit(s) | Affected Package | | Pre-Change Marking Diagram (Microsemi) | Pre-Change Marking Guidelines (Microsemi) | Post-Change Marking Diagram (Microchip) | Post-Change Marking Guidelines (Microchip) | |
| PM | 3.5x4.5 | QFN | ● MSC X XXXX F A YYWWL | Top Mark MSC = Logo X = P for Production, All other Eng XXXX = Part Number F = Fab Code A = Assembly Location YYWW = Date Code L = Lot Code • = Pin 1 location | ● MSC P XXXX YY WWNNN | Top Mark MSC = Logo P = Hardcode P XXXX = Part Number YY = Second two digits of calendar year WWNNN = Trace Code • = Pin 1 location | |
| SNR | ALL | SOIC QSOP DFN | Front XXXXXX XXXXXX YYWWC Backside COO (optional) | Top Mark XXXX = MCHP/Customer Part Number YYWW = Date Code (Year, Work Week) L = Lot Code COO = Assembly Country (Optional) C = Assy Country Code (Optional) | Front XXXXXX XXXXXX YNNNC Backside COO (optional) | Top Mark XXXX = MCHP/Customer Part Number Y = Last Digit of Calendar Year NNN = Trace Code COO = Assembly Country (Optional) C = Assy Country Code (Optional) | |
| | Front + XXX ALL SOT-143 Backside YWWC | | + XXX Backside | Top Mark + = Pin 1 ID XXXX = Part Number YWW = Date Code C = Country Code | + XXX + Backside | Top Mark + = Pin 1 ID XXXX = Part Number NNN = Traceability Code C = Country Code | |

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|-----|-----|----------------------|----------------------------|--|--|----------------------------|--|
| | ALL | ААР | XY | • | Top Mark Where XY is 2 character lot code | NN | Top Mark |
| | | Bump Die Products | • X | Y | assigned by planning | NN | Where NN is last two digits of MCHP trace code (no change to customer) |
| SNR | ALL | | XXXXXX XXX-YYWW | FFFFFF | Top Mark | XXXXXX XXX-YNNN • XXXXXX | Top Mark |
| | | QSOP TSSOP | XXXXXX YYWWL • MSC | YYWW = Date Code (Year, Work Week L = Lot Code | XXXX = MCHP/Customer Part Number YYWW = Date Code (Year, Work Week) L = Lot Code | XXXXXX YYNNN • MSC | XXXX = MSCC/Customer Part Number YY = Last 2 Digits of Calendar Year Y = Last Digit of Calendar Year |
| | | | XXXXXX XXXXXX • YYWW | FFFFFF | FFFF = Fab Lot Number | XXXXXX XXXXXX • YNNN | NNN = Traceability Code |



Frequently Asked Questions (FAQ)

Contacting Microchip: Microchip has Sales Offices Worldwide. You have received this correspondence from a Microchip Inside Sales Representative, please continue to work with him/her to guide you through the transition. Should you need to find your local office, please visit our website at: MicrochipSalesandDistribution. Also note that your current Microsemi contacts have moved to the Microchip email system therefore their email address has changed to firstname.lastname@microchip.com

You may also contact the following individuals within your geography:

Americas: Rozita Yajadda (Rozita.yajadda@microchip.com)

Europe: Wilson (Mary. <u>Wilson@microchip.com</u>)
APAC: Nora Lee (<u>Nora. Lee@microchip.com</u>)

World Wide Distribution: Jennifer Innella (Jennifer.Innella@microchip.com)

EMEA Distribution Jane Afshar (Jane.Afshar@microchip.com)
Asia Distribution: Derek Chan (Derek.Chan@microchip.com)

Open Direct Orders with Microsemi: Open Orders for affected parts will be transferred to the Microchip Systems on or about November 1, 2019. Customers will be contacted by local sales offices prior to the transfer to ensure a smooth transition. All orders will be transferred in US\$ currency. The details of the currency conversion will be outlined by your local ISR contacts closer to the transfer date.

MOQ: Orders must be placed in multiples of tray, tube, bag, or reel size. Additionally, there may be a Purchase Order/Order Line minimum. Existing Microsemi orders being converted to Microchip orders will be subject to the Microchip base quantity multiples and Microchip Purchase Order/Order Line item minimum.

Should changes be required when migrating open backlog, each customer will be notified with full details by your local Inside Sales contact.

Order Acknowledgement: Microchip provides Acknowledgements for all new Direct orders entered and for each change made to an existing Direct order. This document is typically provided via email. Once an existing order is transferred from the Microsemi system to the Microchip system an Order Acknowledgement will then be sent. Customers or Distributors that have an EDI connection will receive either an 855 acknowledgement (US & Asia) or ORDRSP acknowledgement (Europe) via EDI.

Cancel/Reschedule: The table below provides information on the Microchip Cancel/Reschedule policy:

| Catalog PN Restriction | Cancellation | CRD Push Out | CRD Pull In Allowed | CRD Push Out Allowed |
|------------------------|--------------|--------------|------------------------|-------------------------|
| Standard | >30 days PRD | >30 days PRD | Υ | Υ |
| Custom, Non Standard | >60 days PRD | >60 days PRD | Υ | Υ |
| QS9000 | >60 days PRD | >60 days PRD | Υ | Υ |
| NCNR | N/A | N/A | Υ | N |

^{*}CRD – Customer Requested Delivery Date

Advanced Ship Notice (ASN): When placing a Direct Order with Microchip, customers can elect to receive an Advance Ship Notice. This document advises that your order is prepared to ship to the location identified on your Purchase Order. This option will be discussed with you by your local Microchip Contact prior to the go live date in November.

Managing Product Requirements during the Transition: The Microsemi order entry and shipments systems for items identified in this information packet will transition to Microchip systems on or about November 1, 2019. Until that time, please continue to manage your product requirements as you do today. If changes have been made with your local Representative Sales Office, please see the Microchip section Contacting Microchip from above. Microchip will have a 'Quiet Period' that will occur for several days surrounding the final integration so that we can import all existing Purchase Orders into our system. During that time, we will not Accept New Orders, Modify/Cancel Existing Orders, or Ship Product. Please contact your local sales office with any questions or concerns.

Shipping and Invoicing after the transition: After November 1, 2019, all products identified in this phase will be shipped and invoiced from Microchip. Please alert your **Receiving** and **Accounts Payable** departments of this change; in our experience, some clients must cancel existing backlog and then re-issue a new P.O. to Microchip. Over the coming weeks Microchip will contact you to discuss all your needs to insure there is no interruption in your supply chain.

Vendor/Supplier Code: If your system requires a new code to support order placement to Microchip and receive in Microchip shipments, please arrange as needed.

Shipping Labels, Boxes and Packing Methods: Labels, Boxes and Packing methods will be standardized to Microchip's current processes. Special shipping labels for special

^{*}PRD - Microchip Anticipated Delivery Date

products such as programing products, special testing, etc. will adhere to the standard Microchip process over time. See attached Standard Microchip Label Specification.

Lots, Trace Codes, Date Codes, Part Aging, and Shelf Life: Standard Microchip methods for combining production lots, trace codes and date codes into tubes, trays, and reel media will apply as well as standard Microchip Part Aging and Shelf Life Policies. Microchip quality documents and policies including part aging policy are found on our website. QualityDocumentsandPolicies

Payment Terms: Standard payment terms are N30

Terms & Conditions: Microchip Sales are subject to the company's Terms and Conditions ("T&C"). Microchip T&C does differ slightly depending on whether the customer is in the European Union or elsewhere in the world and whether they are purchasing Direct or through microchipDIRECT. Microchip Terms and Conditions are attached.

Product/Process Change Notification (PCN) after the transition: Within the next quarters starting in November 2018 through the year 2020 and potentially into the year 2021 the standard Microchip methods for notifying customers about product changes that include PCNs and End of Life (EOL) notices will begin to apply (please note that this process will integrate over multiple phases of select products during this period). Part of the standard method includes a PCN email service that we expect to be available to select Microsemi customer/product combinations soon after each integration of select products. Once available, customers who wish to receive PCN's via email are expected to register for PCN email service on our PCN web page. Information about how and when to register will be provided in separate integration PCNs as the products you are interested in are phased in. The Microsemi PCN system will continue to be used in conjunction with a partial Microchip PCN system until the full Microchip PCN system can support Microsemi products soon after each group of products have been integrated (review how in the Microsemi Integration PCN's below). The Microsemi PCN system supporting integrated groups of products will be terminated soon after the transition to Microchip systems has completed for each product grouping. Information about Microchip's PCN system can be found at this link: Microchip PCN Website

Microsemi Integration PCN's: Until each product grouping has been integrated into Microchip's PCN system all PCN's related to the integration will be distributed using the Microsemi PCN system and can also be found at this Microchip website: Product Change Notifications. This same PCN distribution process will be used to inform customers to register for the Microchip PCN email distribution process soon after each product grouping has been integrated. Additional integration PCNs for Microsemi products may be issued for the following changes; ordering part numbering convention, shipping labels, shipping boxes, packing methods, part aging/shelf life, top marking, manufacturing site, Bill of Material (BOM), Silicon, and EOL among others.

RoHS Information: Can be found on the Microchip Website under RoHS PB Free, RoHS Device Search. An email will be generated from the system with all of the pertinent information regarding the device search.

http://www.microchip.com/wwwproducts/Rohs/